Overview

HP ProBook 455 G6 Notebook PC



Left

- 1. Internal Microphones (2)
- 2. Webcam
- 3. Webcam LED
- 4. Clickpad
- 5. Hard Drive LED

- 6. SD Card Reader
- 7. Thermal Vent
- 8. USB 2.0 Port
- 9. Security Lock Slot (Lock sold separately)
- 10. Power Button



Overview



Right

- 1. Power Connector
- 2. USB Type-C[™] 3.1 Gen 1 Port
- 3. Ethernet Port (RJ-45)
- 4. HDMI Port (Cable not included)

- 5. USB 3.1 Gen 1 Port
- 6. USB 3.1 Gen 1 Port
- 7. Headphone / Microphone Combo Jack
- 8. Fingerprint Sensor (select models)



Overview

At a Glance

- Preinstall Windows 10 versions or FreeDOS 3.0
- Choice of AMD Ryzen[™] processors
- Display include your choice of 39.62 cm (15.6") diagonal HD, Ultra Wide Viewing Angle FHD
- Integrated AMD Radeon™ Vega UMA Graphics
- Enhanced security features including TPM 2.0, HP BIOSphere, Hardware enforced Firmware Protection, HP Fingerprint Sensor⁴ (select models) and optional IR camera
- Passed 19 items MIL-STD 810G testing plus an additional 120,000 hours of reliability testing through HP's Total Test Process¹
- Weight starting at 4.41 lbs (2 kgs)
- HP Long-Life Rechargeable batteries, with HP Fast Charge Technology recharges 50% in 30 minutes²
- Battery life up to 11 hours
- Supports wireless LAN for connectivity on the go
- Up to 512 GB Solid State Drives and 1 TB Hard Drive
- Up to 16 GB total system memory
- 720p HD webcam, IR camera for face authentication with Windows Hello
- Spill-resistant and optional backlit Keyboard, and Clickpad with multi-touch gestures enabled, taps enabled as default³
- Certified for Skype for business to enhance conferencing experience

1. MIL-STD-810G testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

2. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.

3. Backlit keyboard is an optional feature.

4. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAME

HP ProBook 455 G6 Notebook PC

OPERATING SYSTEMS

Preinstalled

Windows 10 Pro 64¹ Windows 10 Pro 64 (National Academic only)² Windows 10 Home 64¹ Windows 10 Home Single Language 64¹ FreeDOS 3.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information...

PROCESSORS

AMD Ryzen[™] 7 PRO 2700U APU with Radeon[™] RX Vega 10 Graphics (2.2 GHz base clock, up to 3.8 GHz max boost clock, 4 MB L3 cache, 4 cores)^{3,4,5,6}

AMD Ryzen[™] 5 2500U APU with Radeon[™] Vega 8 Graphics (2 GHz base clock, up to 3.6 GHz max boost clock, 4 MB L3 cache, 4 cores) ^{3,4,5,6}

AMD Ryzen[™] 3 2200U APU with Radeon[™] Vega 3 Graphics (2.5 GHz base clock, up to 3.4 GHz max boost clock, 4 MB L3 cache, 2 cores) ^{3,4,5,6}

Processors Family

AMD Ryzen[™] APU processor⁶

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.
 Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
 Max Boost clock frequency performance varies depending on hardware, software and overall system configuration.
 In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor



GRAPHICS

Integrated

Radeon[™] Vega Graphics⁷

Supports

Support HD decode, DX12, HDMI 1.4b

7. HD content required to view HD images.

DISPLAY

Internal Non-Touch

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 45% NTSC, two WLAN antennas (1366 x 768)^{7.8} 39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 45% NTSC, for HD camera, one WLAN antenna (1366 x 768)^{7.8} 39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 45% NTSC, for HD camera, two WLAN antennas (1366 x 768)^{7.8} 39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 45% NTSC, for HD camera, two WLAN antennas (1366 x 768)^{7.8} 39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m², 45% NTSC, for HD + IR camera, two WLAN antennas (1366 x 768)^{7.8}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 45% NTSC, two WLAN antennas (1920 x 1080)^{7,8}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 45% NTSC, for HD camera, one WLAN antenna (1920 x 1080)^{7.8}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 45% NTSC, for HD camera, two WLAN antennas (1920 x 1080)^{7,8}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 45% NTSC, for HD + IR camera, two WLAN antennas (1920 x 1080)^{7,8}

Supports narrow bezel

HDMI

HDMI1.4b, up to 4K 30Hz

7. HD content required to view HD images.

8. Resolutions are dependent upon monitor capability, and resolution and color depth settings.



STORAGE AND DRIVES

Primary Storage 1 TB 5400 rpm SATA⁹ 500 GB 7200 rpm SATA⁹

Primary M.2 Storage

128 GB SATA TLC Solid State Drive⁹ 256 GB PCIe[®] NVMe[™] Value Solid State Drive⁹ 512 GB PCIe[®] NVMe[™] TLC Solid State Drive⁹

9. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum Memory

16 GB DDR4-2400 SDRAM¹⁰

Memory

16 GB DDR4-2400 SDRAM (2 x 8 GB)¹⁰ 12 GB DDR4-2400 SDRAM (1 x 4 GB and 1 x 8 GB)¹⁰ 8 GB DDR4-2400 SDRAM (1 x 8 GB) 8 GB DDR4-2400 SDRAM (2 x 4 GB)¹⁰ 4 GB DDR4-2400 SDRAM (1 x 4 GB)

Memory Slots

2 SODIMM Both slots are customer accessible / upgradeable DDR4 PC4 SODIMMS, system runs at 2400 Supports Dual Channel Memory

10. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Realtek RTL8822BE 802.11ac (2x2) WLAN and Bluetooth[®] 4.2 Combo¹¹ Realtek RTL8821CE 802.11ac (1x1) WLAN and Bluetooth[®] 4.2 Combo¹¹

Ethernet

Realtek RTL8111EP 10/100/1000 NIC12

11. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

12. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.



AUDIO/MULTIMEDIA

Audio

Integrated microphone (Mono or Dual Array) 2 Integrated stereo speakers

Speaker Power

2W/4ohm Per speaker

Camera 720p HD camera⁷ 720p HD camera+IR Camera^{7,13}

7. HD content required to view HD images.

13. Sold separately or as an optional feature.

KEYBOARDS/POINTING DEICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with numeric keypad and optional backlit¹⁴

Pointing Device Clickpad with multi-touch gesture support

Function Keys

- F1 Display Switching
- F2 Blank
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 Blank
- F11 Wireless
- F12 Sleep

Hidden Functions

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock

14. Backlit keyboard is an optional feature.

SOFTWARE AND SECURITY

BIOS

HP BIOSphere Gen4¹⁵ HP DriveLock & Automatic DriveLock¹⁶ BIOS Update via Network Secure Erase¹⁷ Absolute Persistence Module¹⁸ Pre-boot Authentication



HP Wireless Wakeup

Software

HP Native Miracast Support¹⁹ HP LAN-Wireless Protection HP Connection Optimizer HP 3D DriveGuard HP Support Assistant²⁰ HP Noise Cancellation Software HP Host Based MAC Address Manager Buy Office (Sold separately)

Manageability Features

HP Driver Packs²¹ HP System Software Manager (SSM) HP BIOS Config Utility (BCU) HP Client Catalog HP Manageability Integration Kit Gen3²² HP Cloud Recovery²³

Client Security Software

HP Client Security Suite Gen4²⁴ including: HP Security Manager²⁵ (Including Credential Manager, HP Password Manager, HP Spare Key) HP Power On Authentication HP Fingerprint Sensor (select models)²⁹ Microsoft Defender²⁶

Security Management

Secure Erase¹⁷ TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)²⁷ SATA 0,1 port disablement (viaBIOS) Serial, USB enable/disable (viaBIOS) Power-on password (viaBIOS) Setup password (viaBIOS) Support for chassis padlocks and cable lock devices Integrated hood sensor HP Sure Click²⁸

15. HP BIOSphere Gen4 requires Intel[®] or AMD 8th Gen processors. Features may vary depending on the platform and configurations.

16. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives.

17. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.

18. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

19. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming platform and configurations.

20. HP Support Assistant requires Windows and Internet access. 21. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.



Not all configuration components are available in all regions/countries. c06209401 — DA 16350 - Worldwide — Version 12 — May 7, 2020

22. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html

23. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630

24. HP Client Security Suite Gen 4 requires Windows and Intel[®] or AMD 7th or 8th generation processors.
25. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
26. Microsoft Defender Opt in and internet connection required for updates.

27. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT). TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).

28. HP Sure Click is available on most HP PCs and supports Microsoft[®] Internet Explorer and Chromium[™]. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

29. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

POWER

Power Supply

HP Smart 65 W External AC Adapter³⁰ HP Smart 65 W EM External AC Adapter³⁰ HP Smart 65 W USB Type-C [™] Adapter³⁰ HP Smart 45 W External AC power Adapter³⁰ HP Smart 45 W USB Type-C[™] Adapter³⁰

Power Cord

3-wire plug - 1.8 m³⁰ 3-wire plug - 1 m³⁰ 2-wire plug - 1 m³⁰ Duckhead power cord - 1.0 m³⁰ Duckhead power cord - 1.8 m³⁰

Primary Battery

HP Long Life 3-cell, 45 Wh Li-ion Polymer³¹

Battery Life Up to 11 hours³²

Battery Weight

0.48 lb 0.22 kg

30. Availability may vary by country.

31. Battery is internal and not replaceable by customer. Serviceable by warranty.

32. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.



WEIGHTS & DIMENSIONS

Weight

Starting at 4.41 lbs³³ Starting at 2 kgs³³

Dimensions (w x d x h)

14.37 x 10.11 x 0.75 in 36.49 x 25.69 x 1.9 cm

33. Weight will vary by configuration.

PORTS/SLOTS

Ports

1 USB 3.1 Type-C[™] Gen 1 (Power delivery, DisplayPort[™] 1.2) 2 USB 3.1 Gen 1 1 USB 2.0 (Charging) 1 HDMI 1.4b³⁴ 1 RJ-45 1 AC power 1 Headphone/microphone combo jack

Expansion Slots

1 SD Supports SD, SDHC, SDXC

34. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc³⁵

35. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications

SYSTEM UNIT

Stand-Alone	Power	Requirements
(AC Power)		

Nominal Operating Voltage	19V
Average Operating Power	Win 10
Integrated graphics	Data is not available (APU 15W)
Max Operating Power	UMA < 45W
Temperature	
Operating	32° to 95° F (0° to 35° C)
Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	
Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine
Random Vibration	
Operating	0.75 grms
Non-operating	1.50 grms
Altitude (unpressurized)	
•	F_{0} to 10,000 ft (15, 24 to 2,040 m)
Operating Non-operating	-50 to 10,000 ft (-15.24 to 3,048 m) -50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard	-50 10 40,000 11 (-15.24 10 12,152 11)
Certifications	
UL	Yes
CSA	Yes
FCC Compliance	Yes
Energy Star [®]	Selected models ³⁶
EPEAT [®] 2019	Yes, Silver in U.S. ³⁷
ICES	Yes
Australia	Yes
NZ A-Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance	Yes
KC	Yes
BSMI	Yes
CE Marking Compliance	Yes
BNCI or BELUS	Yes
CIT	Yes
GOST	Yes
Saudi Arabian Compliance (ICCP)	Yes



Technical Specifications

SABS	Yes
UKRSERTCOMPUTER	Yes

36. Configurations of the HP ProBook 455 G6 that are ENERGY STAR[®] qualified are identified as HP ProBook 455 G6 ENERGY STAR[®] on HP websites and on http://www.energystar.gov.

37. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 14 inch diagonal	Outline Dimensions (W x H x D)	316.17 x 197.98 (max)
FHD (1920 x 1080) Anti-	Active Area	309.37 x 174.02 (typ.)
Glare WLED UWVA 45% NTSC 250 nits eDP slim	Weight	285 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.2 (2 lane)
	Surface Treatment	Anti-glare
	Touch Enabled	No
	Contrast Ratio	600:1 (typ)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85

Panel LCD 15.6 inch	Outline Dimensions (W x H x D)	350.96 x 216.75 (max.)
	Active Area	344.16 x 193.59 (typ.)
Anti-Glare WLED UWVA 459 NTSC 220nits eDP slim NB	Weight	<370 g max.
	Diagonal Size	15.6"
	Thickness	3.2 mm max.
	Interface	eDP 1.2
	Surface Treatment	Anti-glare
	Touch Enabled	No
	Contrast Ratio	600:1 (typ) - AG
	Refresh Rate	60 Hz
	Brightness	220 nits typical (Panel Only)
hn	5 1	are available in all regions/countries. Iwide — Version 12 — May 7, 2020

	Pixel Resolution Format of LCD Pixel Arrangement Backlight Color Gamut Coverage Color Depth Viewing Angle	1920 x 1080 (FHD) RGB LED 45% of NTSC 6 bits + Hi FRC UWVA 85/85/85
Panel LCD 15.6 inch	Outline Dimensions (W x H x D)	350.96 x 216.75 (max.)
diagonal HD (1366x768)	Active Area	344.16 x 193.59 (typ.)
Anti-Glare WLED SVA 45%	Weight	<370 g max.
NTSC 220nits eDP 1.2 w/o PSR slim NB	Diagonal Size	15.6"
r Sk Stilli ND	Thickness	3.2 mm max.
	Interface	eDP 1.2
	Surface Treatment	Anti-glare
	Touch Enabled	No
	Contrast Ratio	300:1 (typ)
	Refresh Rate	60 Hz
	Brightness	220 nits typical (Panel Only)
	Pixel Resolution	1366 x 768 (HD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits + Hi FRC
	Viewing Angle	SVA 40/40/15/30



Technical Specifications

STORAGE AND DRIVES

HARD DRIVES

500 GB 7200 rpm SATA	Drive Weight	0.20 lb (92 g) ~ 0.21 lb (95 g)
Hard Drive	Rotation speed	7200 rpm
	Cache Buffer	Up to 32 MB
	Height	0.28 in (7 mm)
	Width	2.75 in (69.85 mm)
	Interface	ATA-8, SATA 3.0
	Transfer Rate	600 MB/s
	Seek Time	Single Track: 2 ~ 1.5 ms Average: 11 ~ 13 ms Maximum: 18 ~ 22 ms
	Logical Blocks	976,773,168
	Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
	Security Features	ATA Security
	Features	S.M.A.R.T., NCQ, Ultra DMA
1 TB 5400 rpm SATA Hard	Drive Weight	0.21 lb (94 g)
Drive	Rotation speed	5400 rpm
	Notation speed	5 100 ipin
	Cache Buffer	Up to 32 MB
	-	·
	Cache Buffer	Up to 32 MB
	Cache Buffer Height	Up to 32 MB 0.28 in (7.2 mm)
	Cache Buffer Height Width	Up to 32 MB 0.28 in (7.2 mm) 2.75 in (69.85 mm)
	Cache Buffer Height Width Interface	Up to 32 MB 0.28 in (7.2 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0
	Cache Buffer Height Width Interface Transfer Rate	Up to 32 MB 0.28 in (7.2 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 600 MB/s Single Track2 ms Average12 ~ 13 ms
	Cache Buffer Height Width Interface Transfer Rate Seek Time	Up to 32 MB 0.28 in (7.2 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 600 MB/s Single Track2 ms Average12 ~ 13 ms Maximum18 ~ 22 ms
	Cache Buffer Height Width Interface Transfer Rate Seek Time Logical Blocks	Up to 32 MB 0.28 in (7.2 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 600 MB/s Single Track2 ms Average12 ~ 13 ms Maximum18 ~ 22 ms 1,953,525,168

Features

S.M.A.R.T., NCQ, Ultra DMA



Technical Specifications

SSD 128 GB 2280 M2	Form Factor	M.2 2280
SATA-3 TLC	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ATA-8, SATA 3.0
	Maximum Sequential Read	Up To 520 MB/s
	Maximum Sequential Write	Up To 450 MB/s
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	DIPM; TRIM; DEVSLP
	reatures	
256 GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value Solid State Drive	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3
	Maximum Sequential Read	Up To 1700 MB/s
	Maximum Sequential Write	Up To 1300 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TRIM; L1.2
512 GB 2280 M2 PCIe NVMe	Form Factor	M.2 2280
TLC Solid State Drive	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Up To 2600 MB/s
	Maximum Sequential Write	Up To 1400 MB/s
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TRIM; L1.2



Technical Specifications

NETWORKING/COMMUNICATIONS

Realtek	Wireless LAN Standards	
Realter 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 4.2 Combo ¹	wireiess LMN Stalluarus	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
	Interoperability	Wi-Fi [®] certified
	Frequency Band	802.11b/g/n
		 2.402 - 2.482 GHz 802.11a/n 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11b : +14dBm minimum 802.11g : +12dBm minimum 802.11a : +12dBm minimum 802.11n HT20(2.4GHz) : +12dBm minimum 802.11n HT40(2.4GHz) : +12dBm minimum 802.11n HT20(5GHz) : +10dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum
	Power Consumption	 Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10 mW Radio disabled 8 mW
	Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
	Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum
	Not all configuration c	components are available in all regions/countries.

Not all configuration components are available in all regions/countries. c06209401 — DA 16350 - Worldwide — Version 12 — May 7, 2020

Technical Specifications

Antenna type	802.11a/g, 6Mbp 802.11a/g, 54Mb 802.11n, MCS07 802.11n, MCS15 802.11ac, MCS0 802.11ac, MCS9 High efficiency a enclosure	s : -84dBm maximum os : -86dBm maximum ops : -72dBm maximum : -67dBm maximum : -64dBm maximum : -84dBm maximum : -59dBm maximum ntenna with spatial diversity, mounted in the display
	support WLAN M	dual band 2.4/5 GHz antennas are provided to the card to IMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Туре 2230: 2.3 х	22.0 x 30.0 mm
Weight	Туре 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	Operating: 14° to 158° F (–10° to 70° C) Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating Non-operating	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	
HP Integrated Module wit	h Bluetooth 4.0/4.	.1/4.2 Wireless Technology
Bluetooth® Specification	4.0/4.1/4.2 Compliant	
Frequency Band	2402 to 2480 MH	łz
Number of Available Channels	Legacy: 0~79 (1 BLE: 0~39 (2 MHz	
Signaling Data Rate ⁴	Legacy: 3 Mbps Signaling Data Rate 2.17 Mbps BLE: 1 Mbps Signaling Data Rate 0.2 Mbps	

	1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950



	Bluetooth Profiles Supported	UL, CSA, and CE Mark BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
	 Maximum output power Receiver sensitivity is me 	iver release for updates on supported security features. may vary by country according to local regulations. easured at a packet error rate of 8% for 802.11b (CKK modulation) and a r 802.11a/g (OFDM modulation). ary
Realtek 802.11a/b/g/n/ac (1x1) WLAN and Bluetooth® 4.2 Combo ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
	Interoperability Frequency Band	Wi-Fi [®] certified 802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification



	• IEEE 802.11i		
	• WAPI		
Network Architecture Models	Ad-hoc (Peer to I Infrastructure (A	Peer) ccess Point Required)	
Roaming	IEEE 802.11 com	pliant roaming between access points	
Output Power ²	• 802.11b : +14d	Bm minimum	
	• 802.11g : +12d	Bm minimum	
	• 802.11a : +12d	Bm minimum	
		2.4GHz) : +12dBm minimum	
		2.4GHz) : +12dBm minimum	
	-	5GHz) : +10dBm minimum	
	-	5GHz) : +10dBm minimum	
		0(5GHz) : +10dBm minimum	
Power Consumption	 Transmit mode Receive mode 1 		
) 180 mW (WLAN Associated)	
	-	W (WLAN unassociated)	
	Connected Star	•	
	Radio disabled	•	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode		
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum		
Antenna type		ntenna. lual band 2.4/5 GHz antenna is provided to the card to ommunications and Bluetooth communications	
Form Factor	PCI-Express M.2	MiniCard	
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230 : 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	Operating: 14° to 158° F (–10° to 70° C) Non-operating: –40° to 176° F (–40° to 80° C)	
Humidity	Operating Non-operating	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)	
Altitude	Operating Non-operating	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Rac	lio OFF; LED White – Radio ON	
HP Integrated Module wit	h Bluetooth 4.0/4.	1/4.2 Wireless Technology	

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless TechnologyBluetooth Specification4.0/4.1/4.2 CompliantFrequency Band2402 to 2480 MHzNumber of AvailableLegacy: 0~79 (1 MHz/CH)ChannelsBLE: 0~39 (2 MHz/CH)



Signaling Data Rate⁴	Legacy: 3 Mbps Signaling Data Rate 2.17 Mbps BLE: 1 Mbps Signaling Data Rate 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps
	asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Check latest software/driver release for updates on supported security features.
 Maximum output power may vary by country according to local regulations.
 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

4. Actual throughput may vary.



Technical Specifications

POWER

FUWER				
HP 45 W Smart	Dimensions (H x W x D)	3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm) 0.386 lb (175 g) max		
AC adapter	Weight			
	Input	90 to 265 VAC		
		Input Efficiency	87.74% at 115Vac and 88.4% at 230Va	
		Input frequency range	47 to 63 Hz	
		Input AC current	1.4 A at 90 VAC	
	Output	Output power	45W	
		DC output	19.5V	
		Hold-up time	5 msec at 115 VAC input	
		Output current limit	<8.0A	
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords		
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)	
		Altitude	0 to 16,400 ft (0 to 5,000 m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
	Certifications	* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.		
HP 65 W Smart	Dimensions	90 x 51 x 28.5 mm		
AC adapter	Weight	unit: 220 g +/- 10 g		
	Input	Input Efficiency	88% min at 115 VAC and 89% min at 230 VAC	
		Input frequency range	47 to 63 Hz	
		Input AC current	Max. 1.7 A at 90 VAC	
	Output	Output power	65W	
		DC output	19.5V	
		Hold-up time	5 msec at 115 VAC input	
		Output current limit	<11.0A	
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable co		
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)	
		temperature	-4°F to 185°F (-20°to 85°C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	20% to 95%	



Technical Specifications

		Storage Humidity	10% to 95%	
	EMI and Safety	*CE Mark - full compliance	with LVD and EMC directives	
	Certifications	* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.		
		* MTBF - over 200,000 hou	urs at 25°C ambient condition.	
HP 65 W EM Smart AC	Dimensions	102 x 55 x 30 mm		
adapter	Weight	270g +/- 10g		
	-	Input Efficiency	87% min at 115V/230V	
		Input frequency range	47 to 63 Hz	
		Input AC current	1.7 A at 90 VAC and maximum load	
		DC output	65W(19.5V/3.33A)	
		Hold-up time	5 msec at 115 VAC input	
		Output current limit	<11A, Over voltage protection- 29V max automatic shutdown	
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords		
	Environmental Design	Operating temperature	0° to 35° C	
		Non-operating (storage) temperature	-20° to 85° C	
		Altitude	0 to 5,000 m	
		Humidity	0% to 95%	
		Storage Humidity	0% to 95%	
	EMI and Safety Certifications	*CE Mark - full compliance	with LVD and EMC directives	
		* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.		
		* Reliability - failure rate of years of operation	of less than 0.1% annually within the first thre	
AC Adapter 65 Watt nPFC	Dimensions	74 x 74 x 28.5 mm		
USB type C	Weight	unit: 245 g +/- 10 g		
	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A	
		Input frequency range	47 to 63 Hz	
		Input AC current	1.7 A at 90 VAC and maximum load	



Technical Specifications

•				
		DC output	5V/9V/10V/12V/15V/20V	
		Hold-up time 5ms at 115 Vac input		
		Output current limit	<8.0A	
	Connector	Туре С		
	Environmental Design	Operating temperature	32° F to 95° F (0° to 35° C)	
		Non-operating (storage) temperature	-4° F to 185° F (-20° to 85° C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	5% to 95%	
		Storage Humidity	5% to 95%	
	EMI and Safety	*CE Mark - full compliance	e with LVD and EMC directives	
	Certifications	SELV; Agency approvals - FCC Class B, CISPR22 Class	ards - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, s B, CCC, NOM-1 NYCE. urs at 25°C ambient condition.	
AC Adapter 45 Watt nPFC	Dimensions	62.0 x 62.0 x 28.5 mm		
USB type C	Weight	unit: 220 g +/- 10 g		
	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100%	
	input	input Lincicity	load condition with 115Vac/230Vac Spec:5V: 81.5%9V: 86.7%10V: 87.5%12V : 87.8%15V: 87.8%20V: 87.8%	
		Input frequency range	47 to 63 Hz	
		Input AC current	Max. 1.4 A at 90 Vac	
		Output power	5V/15W 9V/27W 10V/37.5W 12V/45W 15V/45W 20V/45W	
		DC output	5V/9V/10V/12V/15V/20V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<5.0A	
	Connector	Туре С		
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)	
		temperature	-4°F to 185°F (-20°to 85°C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
		*CE Mark - full compliance	with LVD and EMC directives	



Technical Specifications

EMI and Safety Certifications	* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.
	* MTBF - over 200,000 hours at 25°C ambient condition.

3 Cell WHr 45 Long Life -	Dimensions (H x W x L)	6.0. x184.7x88.9 mm
Polymer HP Fast Charge Technology	Weight	0.22 kg (0.48 lb)
	Cells/Type	3cell Lithium-Ion
	Voltage	11.55V
	Amp-hour capacity	3.900Ah
	Watt-hour capacity	45Wh
	Operating (Charging)	32° to 113° F (0° to 45° C)
	Operating (Discharging)	14° to 122° F (-10° to 60° C)
	Optional Travel Battery Available	No

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations System Configuration	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] EPEAT registered in the United States. See http://www.epeat.net for registration status in your country. The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook". 			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	7.4	7.59	7.42	
Normal Operation (Long idle)	4.8	4.95	5	
Sleep	0.5	0.57	0.5	
Off	0.3	0.34	0.3	

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.



Heat Dissipation*	115	VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)		25	26	25
Normal Operation (Long idle)		16	17	17
Sleep		2	2	2
Off NOTE:		1	1	1
NOTE.	Heat dissipati for one hour.	ion is calculated ba	sed on the measured watts, as	suming the service level is attained
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle		3		27
Fixed Disk – Random writes		3		27
Longevity and Upgrading			ossibly extending its useful life ntained in the product may incl	e by several years. Upgradeable ude:
Batteries			omply with EU Directive 2006/6	
	Batteries used in the product do not contain: Mercury greater the1ppm by weight			
	Cadmium grea	ater than 20ppm b	y weight	
	Battery size: (Battery type:	CR2032 (coin cell) Lithium		
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.			
	This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.			
			liance with California Proposition (ic Enforcement Act of 1986).	on 65 (State of California; Safe
	• This	-	liance with the IEEE 1680.1 (EP	EAT) standard at the <silver> level,</silver>
		tics parts weighing		duct are marked per ISO11469 and
			% post-consumer recycled pla ecycle-able when properly disp	
Packaging Materials	External:	PAPER/Corruga		295 g
	Internal:		xpanded Polyethylene) thylene low density - LDPE	68 g 10 g
Material Usage	to the HP Gen	does not contain a leral Specification f		in excess of regulatory limits (refer
	• Asbe			
	Certain Azo Colorants Contain Received Eleme Retendents - movement he used as flows extendents in plastics			
	 Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium 			
		rinated Hydrocarbo	ons	
		rinated Paraffins		
		naldehyde genated Diphenyl I	Methanes	
			ts are available in all regions/coun	tries.
DD			rldwide — Version 12 — May 7, 20	

Technical Specifications

	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	 Nickel – finishes must not be used on the external surface designed to be frequently
	handled or carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	• Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
	Radioactive Substances
	 Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	• Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	 Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ ISO_14K_Certificate.pdf
	and http://www.bp.com/bpinfo/globalcitizonship/onvironmont/pdf/cort.pdf
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA#xxx
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Essential Messenger Case (up to 17.3")	H1D25AA
Docking	HP USB-C Mini Dock	1PM64AA#xxx
	HP USB-C Universal Dock	1MK33AA#xxx
	HP USB-C Dock G4	3FF69AA#xxx
	HP TB Dock 120W w/Audio	3YE87AA#xxx
	HP Thunderbolt Dock 120W G2	2UK37AA#xxx
	HP TB Dock G2 w/ Combo Cable	3TR87AA#xxx
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA
	HP USB Travel Dock	T0K30AA#xxx
	DIB HP 400G6 HDD Bracket Kit	5LV47AV
Input / Output	HDMI to VGA Adapter	H4F02AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP USB-C to VGA Adapter	N9K76AA
	HP Stereo 3.5 mm Headset	T1A66AA
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP USB Collaboration Keyboard	Z9N38AA#xxx
	HP UC Speaker Phone	K7V16AA
Power	HP Power Bank	N9F71AA#xxx
	HP 45W LC USB-C Power Adapter	1MZ01AA#ABA
	HP 45W Smart AC Adapter 4.5mm	H6Y88AA#xxx
	HP 65W Slim AC Adapter	H6Y82AA#xxx
	HP 65W USB-C Power Adapter	3PN48AA
	HP 45W USB-C Power Adapter	1HE07AA#xxx
	HP 65W USB-C Power Adapter	1HE08AA#xxx
	HP USB-C Power Bank	2NA10AA#xxx
Storage	HP External USB Optical Drive	F2B56AA
	HP 500GB 7200rpm HDD	F3B97AA
	HP 512GB TLC PCI-e 3x4 NVMe SSD (2280)	1FU88AA
	4GB 2666MHz DDR4	4VN05AA
	8GB 2666MHz DDR4	4VN06AA
	Not all configuration components are available in all regions (cour	atrias



Options and Accessories (sold separately and availability may vary by country)

	16GB 2666 MHz DDR4	4VN07AA
Security	HP Essential Keyed Cable lock 12.3mm	T0Y14AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Combination Lock	TOY15AA
Displays	HP ProDisplay P240va 23.8 inch Monitor	N3H14AA
	HP ProDisplay P232 23 inch Monitor	K7X31AA
	HP EliteDisplay E223 21.5 inch Monitor	1FH45AA
	HP EliteDisplay E243 23.8-inch Monitor	1FH47AA
	HP EliteDisplay S14 14-inch Portable Display	3HX46AA



Summary of Changes

Date of change:	Version History:		Description of change:
March 11, 2019	V1 to V2	Updated	Networking section
April 9, 2019	V2 to V3	Updated	Environmental data table added
April 10, 2019	V3 to V4	Updated	Items MIL-STD 810G testing corrected
April 17, 2019	V4 to V5	Updated	MIL-STD
June 10, 2019	V5 to V6	Added	HP Cloud Recovery
July 5, 2019	V6 to V7	Updated	Color Gamut
July 23, 2019	V7 to V8	Added	Speaker to Audio section
September 20, 2019	V8 to V9	Updated	Security Lock Slot and 250nits Panel
October 11, 2019	V9 to V10	Added	DisplayPort™ 1.2
February 27, 2020	V10 to V11	Updated	Copyright and footnote for fingerprint sensor
May 7, 2020	V11 to V12	Updated	Ethernet Section

Copyright © 2020 HP Development Company, L.P. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

AMD, Ryzen and Radeon are trademarks of Advanced Micro Devices, Inc. Bluetooth is a trademark owned by its proprietor and used by HP Inc. under license. DisplayPort[™] and the DisplayPort[™] logo are trademarks owned by the Video Electronics Standards Association (VESA®) in the United States and other countries. USB Type-C[™] and USB-C[™] are trademarks of USB Implementers Forum. SD, SDHC and SDXC are registered trademarks of SD-3C in the United States, other countries or both. ENERGY STAR is a registered trademark of the U.S. Environmental Protection Agency. Microsoft and Windows are either registered trademarks or trademarks of Microsoft Corporation in the United States and/or other countries

